

客户图

NOTES:

1:MATERIAL

- 1.1 HOUSING: Polyester(LCP)BLACK,UL94 V-0
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, TIN PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.

2:ELECTRICAL:

- 2.1 CURRENT RATING: 1.2A(4pins powered).
- 2.2 VOLTAGE RATING: 150VAC/212VDC.
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
- 2.4 CONTACT RESISTANCE: 100mΩ MAX.
- 2.5 INSULATION RESISTANCE: 1000 mΩ Min
- 2.6 Operation Temperature:-55°C to +125°C

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN, NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

66B4-F-XX-04-GX-036-R-01

SEE:TABLE 1
No.OF POS
-10
-20
...
-100

SEE:TABLE 2
No OF ROWS
-04

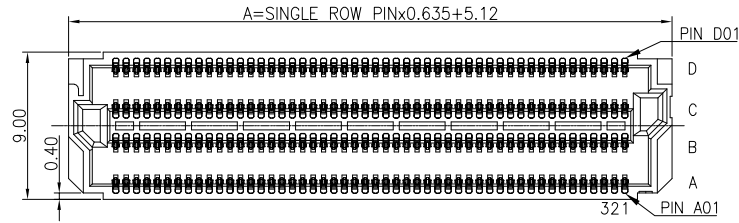
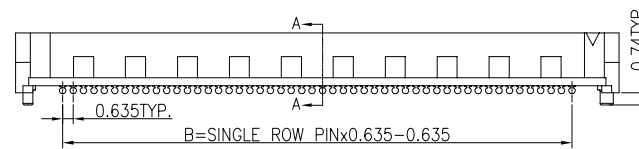
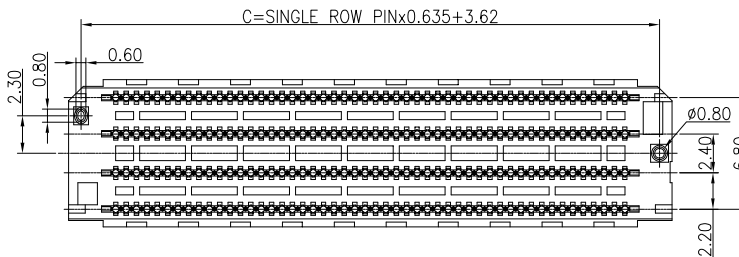
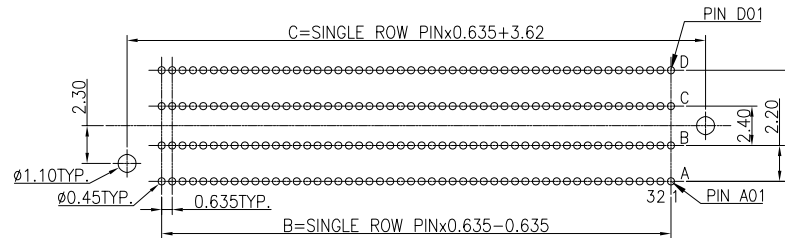
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G6=30u" Gold

塑胶高度: 036=3.66mm

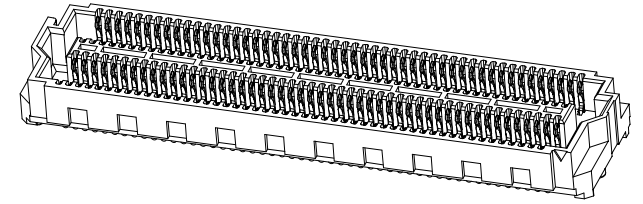
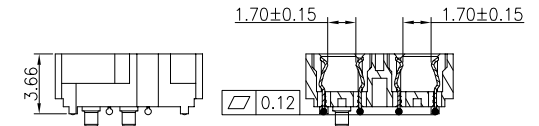
包装方式:
R=载带包装

TABLE 1

No.OF POS	"A"	"B"	"C"
-10	11.47	5.715	9.97
-20	17.82	12.065	16.32
-30	24.17	18.415	22.67
-40	30.52	24.765	29.02
-50	36.87	31.115	35.37
-60	43.22	37.465	41.72
-70	49.57	43.815	48.07
-80	55.92	50.165	54.42
-90	62.27	56.515	60.77
-100	68.62	62.865	62.23



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05



H						OPERATION		DRAW		Mr.Zeng		2026.08.04		SOLEPiN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
						X.X	±0.40	DESIGN		Jensen		2026.08.04						
						X.XX	±0.25	CHECK		Jack		2026.08.04		SIZE	A4	PART NO.	66B4-F-XX-04-GX-036-R-01	
						X.XXX	±0.15	APPROVE		Andy		2026.08.04		SHEET	1/1	TITLE:	0.635mm PITCH SOCKET APPAY ASSEMBLY	
	A0		NEW			Angle	±3°							SHEET	1/1	TITLE:	0.635mm PITCH SOCKET APPAY ASSEMBLY	
	REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-2127		

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- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST

4.Max Processing Temp:265°C Seconds 40S

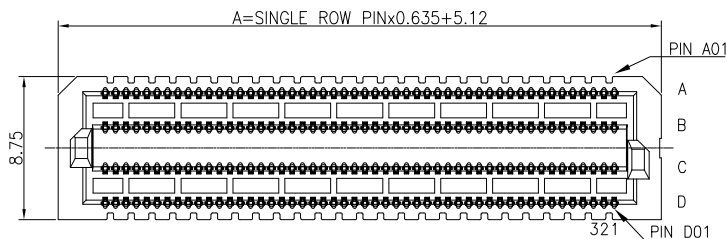
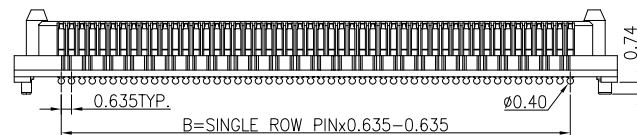
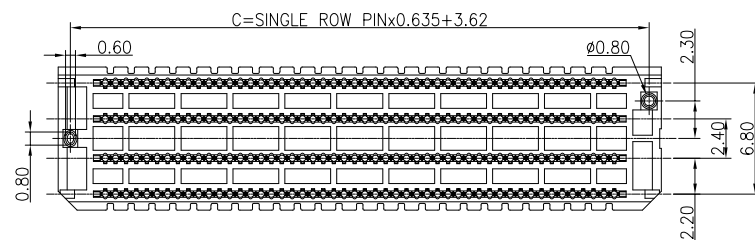
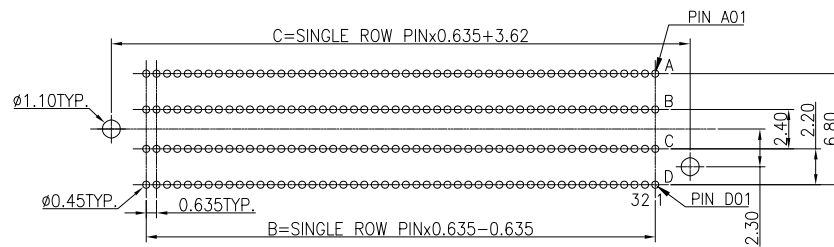
5.ORDER INFORMATION:

66B4-M-XX-04-GX-037-R-01

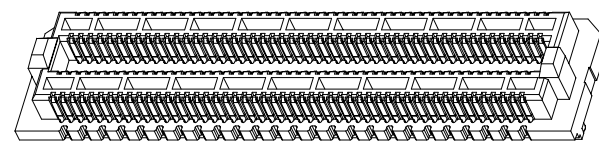
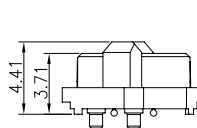
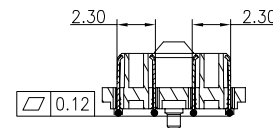
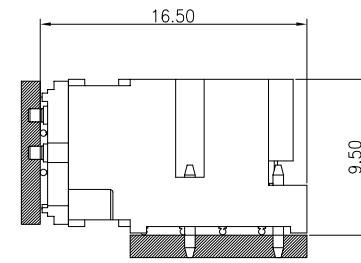
No.OF POS:	端子电镀:	塑胶高度:	包装方式:
-10	G0=Gold Flash	037=3.71mm	R=载带包装
-20	No OF ROWS:	G1=1u" Gold	
...	-04	G2=3u" Gold	
-100		G3=5u" Gold	
		G4=10u" Gold	
		G6=30u" Gold	

TABLE 1

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RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05



MATING HEIGHT

OPERATION		DRAW	Mr.Zeng	2026.08.04
X.X	±0.40	DESIGN	Jensen	2026.08.04
X.XX	±0.25	CHECK	Jack	2026.08.04
X.XXX	±0.15	APPROVE	Andy	2026.08.04
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	PROJ.	mm	SCALE 1:1

SOLEPiN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	66B4-M-XX-04-GX-037-R-01
SHEET	1/1	TITLE:	0.635mm PITCH TERMINAL APPAY ASSEMBLY
PROJ.	Φ	DRAW NO.	SP-2126

客户图

NOTES:

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4.Max Processing Temp:265°C Seconds 40S

5.ORDER INFORMATION:

66B4R-F-XX-04-GX-094-R-01

SEE:TABLE 1

No.OF POS

-10

-20

...

-100

SEE:TABLE 2

No OF ROWS

-04

端子电镀:

G0=Gold Flash

G1=1u" Gold

G2=3u" Gold

G3=5u" Gold

G4=10u" Gold

G6=30u" Gold

塑胶高度:

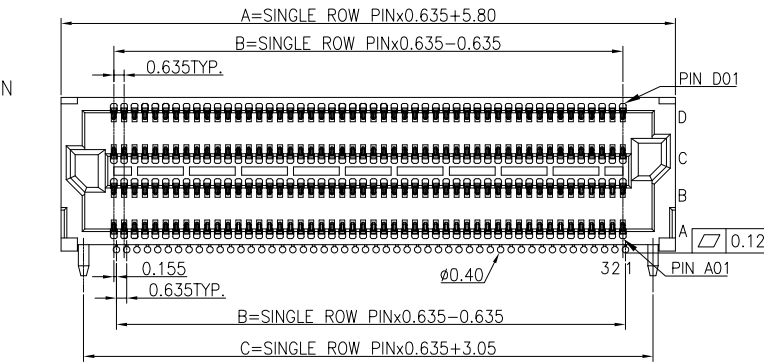
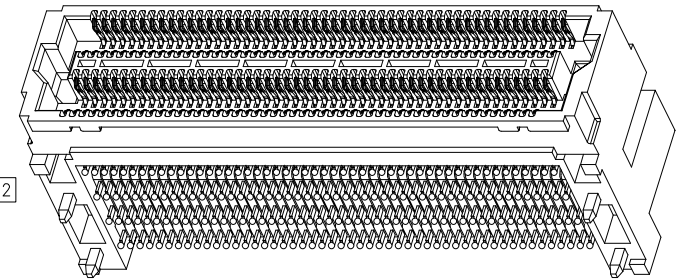
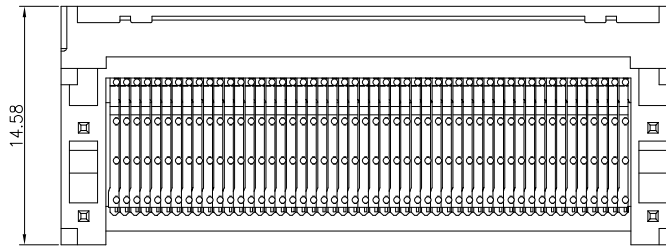
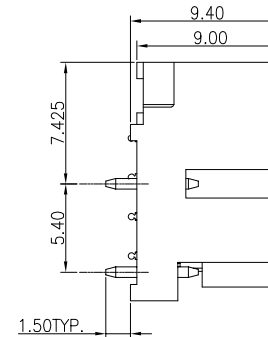
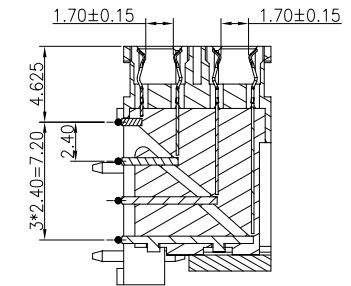
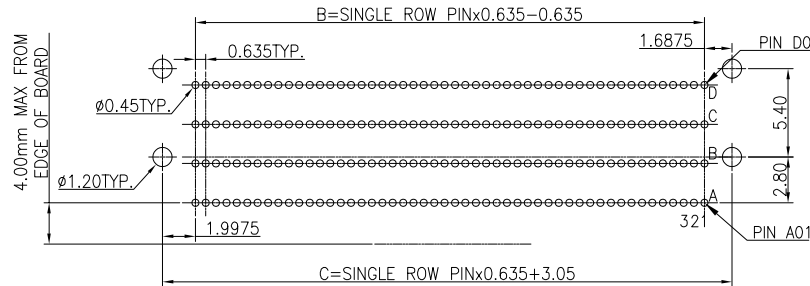
094=9.40mm

包装方式:

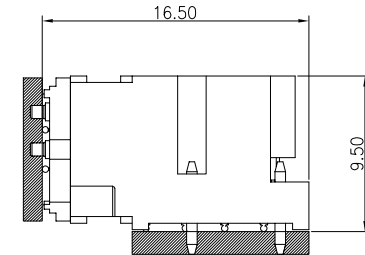
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RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE ±0.05



MATING HEIGHT

OPERATION

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

DRAW

DESIGN

CHECK

APPROVE

UNIT

Mr.Zeng

Jensen

Jack

Andy

mm

2026.08.04

2026.08.04

2026.08.04

2026.08.04

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 66B4R-F-XX-04-GX-094-R-01

SHEET 1/1 TITLE: 0.635mm PITCH 90° SOCKET APPAY ASSEMBLY

PROJ. DRAW NO. SP-2127

AO

REV

1

2

3

4

5

6

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10